SFH 4770

SYNIOS® P2720

IR SYNIOS P2720 (850 nm) - 120°









Applications

- CCTV Surveillance

- Safety and Security, CCTV

Eye Tracking

Features:

- Package: clear silicone

- Corrosion Robustness Class: 3B

- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)

- IR lightsource with high efficiency

- Low thermal resistance (Max. 10 K/W)

- Centroid wavelength 850 nm

Ordering Information

Type Total radiant flux 1) Total radiant flux 1) Ordering Code

 $I_{F} = 1000 \text{ mA}; t_{p} = 10 \text{ ms}$ $I_{F} = 1000 \text{ mA}; t_{p} = 10 \text{ ms}$

SFH 4770 450 ... 900 mW 600 mW Q65112A1540

Maximum Ratings

T_A = 25 °C

Parameter	Symbol		Values
Operating temperature	T _{op}	min.	-40 °C
		max.	100 °C
Storage temperature	T_{stg}	min.	-40 °C
	2.9	max.	100 °C
Junction temperature	T_{j}	max.	145 °C
Forward current	I _F	max.	2000 mA
Surge current	I _{FSM}	max.	3 A
$t_p \le 2 \text{ ms}; D = 0.005$			
Reverse voltage ²⁾	V_R	max.	5 V
Power consumption	P _{tot}	max.	3.45 W
ESD withstand voltage	V_{ESD}	max.	2 kV
acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	205		

For the forward current and power consumption please see "maximum permisssible forward current" diagram



Characteristics

 $I_{\scriptscriptstyle F}$ = 1000 mA; $t_{\scriptscriptstyle p}$ = 10 ms; $T_{\scriptscriptstyle A}$ = 25 °C

ameter Symbol			Values	
Peak wavelength	λ_{peak}	typ.	860 nm	
Centroid wavelength	$\lambda_{ ext{centroid}}$	typ.	850 nm	
Spectral bandwidth at 50% I _{rel,max} (FWHM)	Δλ	typ.	30 nm	
Half angle	φ	typ.	60 °	
Dimensions of active chip area	LxW	typ.	1 x 1 mm x mm	
Rise time (10% / 90%) $I_F = 3 \text{ A}; R_L = 50 \Omega$	t _r	typ.	11 ns	
Fall time (10% / 90%) $I_F = 3 \text{ A}; R_L = 50 \Omega$	t _f	typ.	14 ns	
Forward voltage	V_{F}	typ. max.	1.65 V 2.1 V	
Forward voltage $I_F = 2 \text{ A}; t_p = 100 \mu\text{s}$	V_{F}	typ. max.	1.9 V 2.5 V	
Forward voltage $I_F = 3 \text{ A}; t_p = 100 \mu\text{s}$	V_{F}	typ. max.	2.15 V 3 V	
Reverse current ²⁾ V _R = 5 V	l _R	max.	10 μΑ	
Radiant intensity	l _e	typ.	200 mW/sr	
Radiant intensity $I_F = 2 \text{ A}$; $t_p = 100 \mu\text{s}$	l _e	typ.	370 mW/sr	
Total radiant flux ¹⁾ $I_F = 2 \text{ A}; t_p = 100 \mu\text{s}$	Фе	typ.	1110 mW	
Temperature coefficient of voltage	TC_{v}	typ.	-1 mV / K	
Temperature coefficient of brightness	TC,	typ.	-0.3 % / K	
Temperature coefficient of wavelength	TC_{λ}	typ.	0.3 nm / K	
Thermal resistance junction solder point real 3)	R_{thJS}	typ. max.	6.5 K / W 10.0 K / W	



Brightness Groups

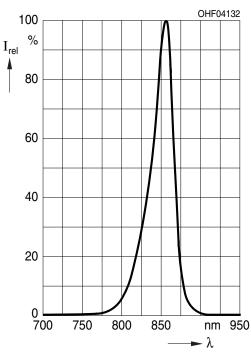
T_A = 25 °C

Group	Total radiant flux $^{1)}$ I _F = 1000 mA; t _p = 10 ms min. $\Phi_{\rm e}$	Total radiant flux $^{1)}$ $I_F = 1000 \text{ mA}$; $t_p = 10 \text{ ms}$ max. Φ_e
DA2	450 mW	630 mW
DB	500 mW	800 mW
EA1	630 mW	900 mW

Only one group in one packing unit (variation lower 1.6:1).

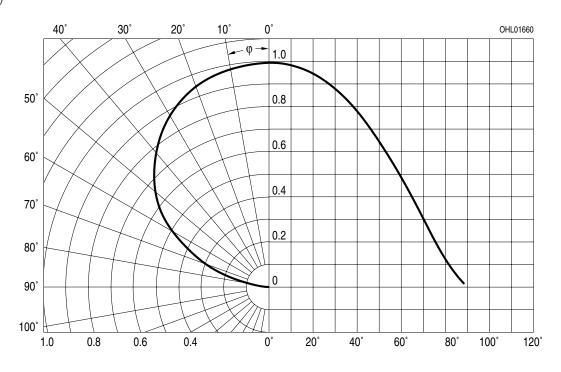
Relative Spectral Emission 4), 5)

 $I_{e,rel} = f(\lambda); I_F = 1000 \text{ mA}; t_p = 10 \text{ ms}$



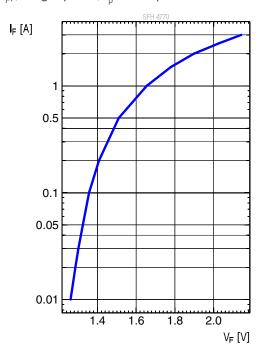
Radiation Characteristics 4), 5)

$$I_{e,rel} = f(\phi)$$



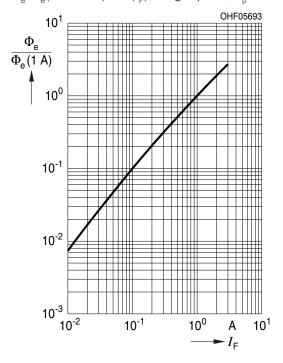
Forward current 4), 5)

 $I_F = f(V_F)$; single pulse; $t_D = 100 \mu s$



Relative Total Radiant Flux 4), 5)

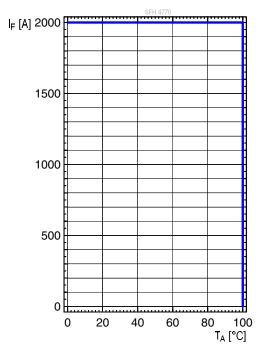
 $\Phi_{\rm e}/\Phi_{\rm e}(1000{\rm mA})$ = f (I_F); single pulse; t_p = 100 $\mu {\rm s}$



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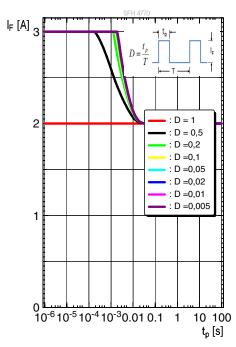
Max. Permissible Forward Current

$$I_{F,max} = f(T_S); R_{thJS} = 10.0 \text{ K/W}$$



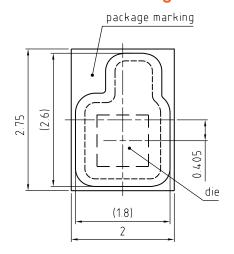
Permissible Pulse Handling Capability

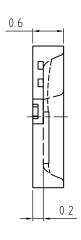
 $I_F = f(t_p)$; duty cycle D = parameter; $T_S = 85$ °C

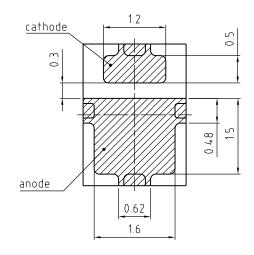




Dimensional Drawing 6)







General tolerance ±0.1

Lead finish Au

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Further Information

Approximate Weight: 12.0 mg

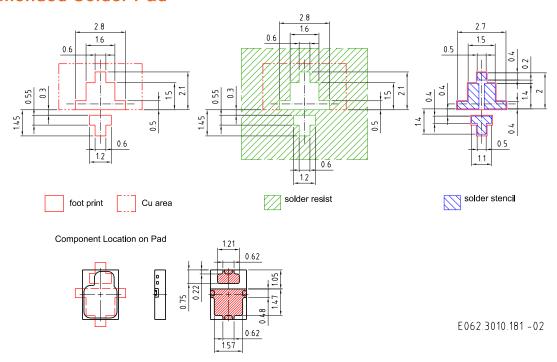
Package marking: Cathode

Corrosion test: Class: 3B

Test condition: 40°C / 90 % RH / 15 ppm H₂S / 14 days (stricter than IEC

60068-2-43)

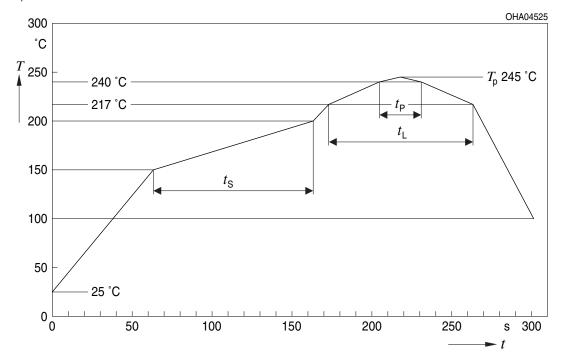
Recommended Solder Pad 6)



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Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



Profile Feature	Symbol Pb-Free (SnAgCu) Assembly		Unit		
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*)			2	3	K/s
25 °C to 150 °C					
Time t _s	t_s	60	100	120	S
T_{Smin} to T_{Smax}					
Ramp-up rate to peak*)			2	3	K/s
T_{Smax} to T_{P}					
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	$t_{\scriptscriptstyle \perp}$		80	100	S
Peak temperature	T_{P}		245	260	°C
Time within 5 °C of the specified peak	t _P	10	20	30	S
temperature T _P - 5 K					
Ramp-down rate*			3	6	K/s
T _P to 100 °C					
Time				480	S
25 °C to T _P					

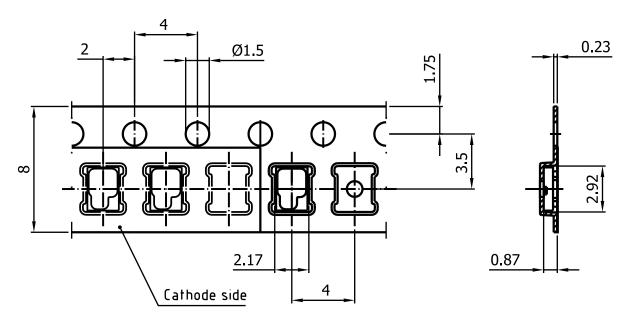
All temperatures refer to the center of the package, measured on the top of the component



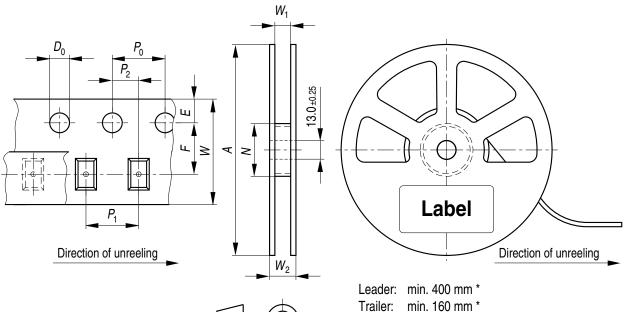
^{*} slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

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Taping 6)



C67062-A0116-B14-04



Reel Dimensions

Α	W	N_{\min}	W ₁	$W_{2\mathrm{max}}$	Pieces per PU
180 mm	8 + 0.3 / - 0.1 mm	60 mm	8.4 + 2 mm	14.4 mm	2000

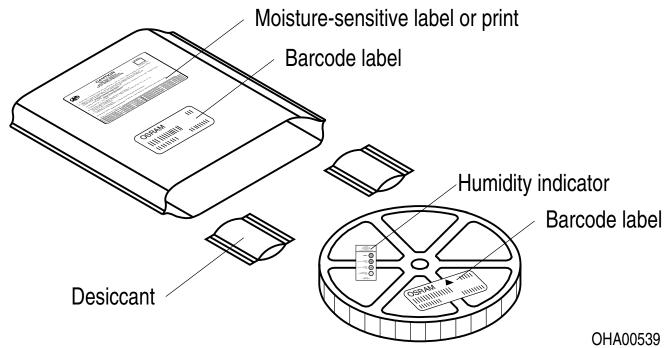
*) Dimensions acc. to IEC 60286-3; EIA 481-D

OHAY0324

Barcode-Product-Label (BPL)

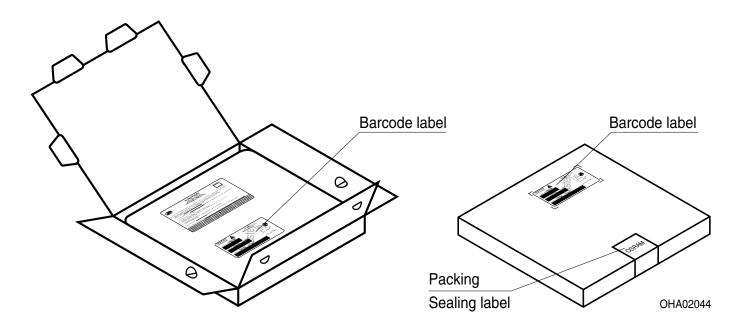


Dry Packing Process and Materials 6)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

Schematic Transportation Box 6)



Dimensions of Transportation Box

Width	Length	Height
200 ± 5 mm	195 ± 5 mm	30 ± 5 mm

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Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes

Discontinued

Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

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OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

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Glossary

- Total radiant flux: Measured with integrating sphere.
- Reverse Operation: Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- Thermal resistance: junction soldering point, of the device only, mounted on an ideal heatsink (e.g. metal block)
- Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- ⁵⁾ **Testing temperature:** TA = 25°C (unless otherwise specified)
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- ⁷⁾ **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

Revision History		
Version	Date	Change
1.0	2019-01-23	Initial Version
1.1	2019-07-15	Discontinued



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